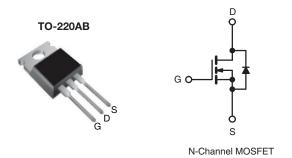
Vishay Siliconix

HALOGEN FREE

E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	700				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.18				
Q _g max. (nC)	110				
Q _{gs} (nC)	15				
Q _{gd} (nC)	32				
Configuration	Single				



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Liahtina
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP22N65E-E3			
Lead (Pb)-free and Halogen-free	SiHP22N65E-GE3			

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	650	V	
Gate-Source Voltage			V_{GS}	± 30	V	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	22	А	
		T _C = 100 °C		14		
Pulsed Drain Current ^a			I _{DM}	56		
Linear Derating Factor				1.8	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	691	mJ	
Maximum Power Dissipation			P_{D}	227	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	70	- V/ns		
Reverse Diode dV/dt ^d			26			
Soldering Recommendations (Peak Temperature) c for 10 s				300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.55	C/VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•			•	•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.74	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Oala Oa aa laalaa	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Gate-Source Leakage			$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ
Zoro Coto Voltago Drain Current	1	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$		-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 520 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A		0.15	0.18	Ω
Forward Transconductance	9 _{fs}	V _D	_S = 8 V, I _D = 5 A	-	6.7	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,		2415	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	=.	118	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		4	-	pF
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	89	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	307	-	
Total Gate Charge	Qg			-	73	110	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 520 \text{ V}$		15	-	nC
Gate-Drain Charge	Q _{gd}	1			32	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 520 V, I _D = 11 A,		-	22	45	
Rise Time	t _r			-	33	66	
Turn-Off Delay Time	t _{d(off)}	V _{GS} :	= 10 V, $R_g = 9.1 \Omega$	-	73	110	ns
Fall Time	t _f		1		38	76	1
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.64	-	Ω
Drain-Source Body Diode Characteristic	s	_					
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	22	
Pulsed Diode Forward Current	I _{SM}			-	-	56	A .
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 11 A, dl/dt = 100 A/μs, V _R = 400 V		-	400	-	ns
Reverse Recovery Charge	Q _{rr}			-	5.9	-	μC
Reverse Recovery Current	I _{RRM}			_	20	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

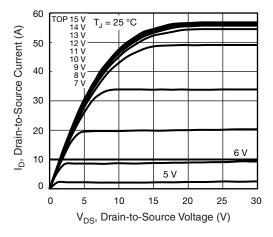


Fig. 1 - Typical Output Characteristics

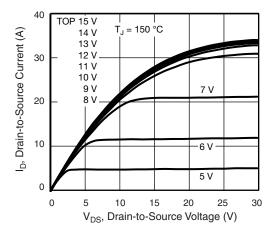


Fig. 2 - Typical Output Characteristics

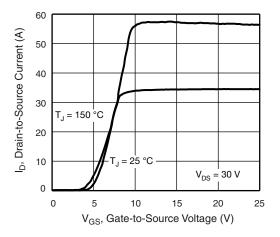


Fig. 3 - Typical Transfer Characteristics

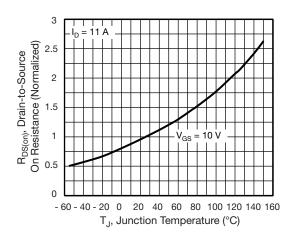


Fig. 4 - Normalized On-Resistance vs. Temperature

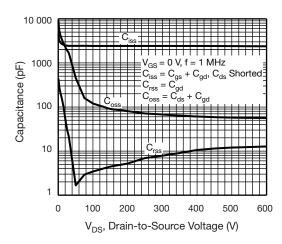


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

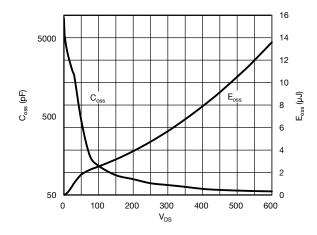


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



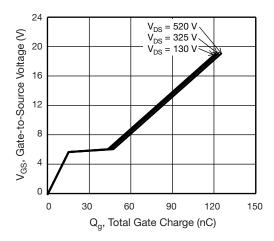


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

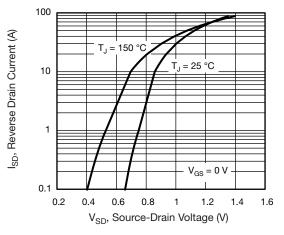


Fig. 8 - Typical Source-Drain Diode Forward Voltage

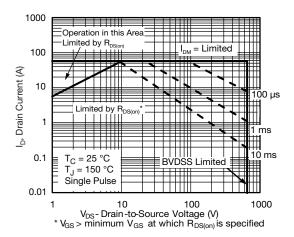


Fig. 9 - Maximum Safe Operating Area

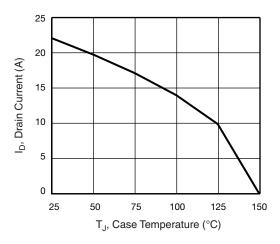


Fig. 10 - Maximum Drain Current vs. Case Temperature

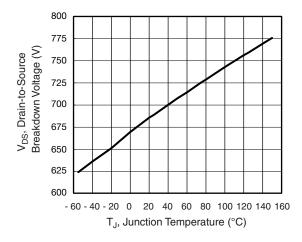


Fig. 11 - Temperature vs. Drain-to-Source Voltage



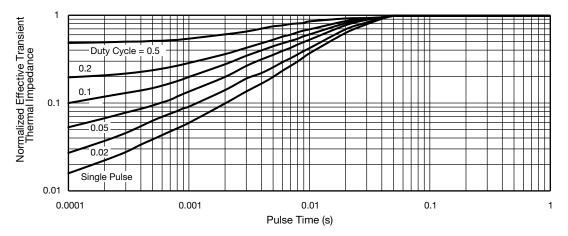


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

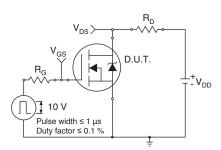


Fig. 13 - Switching Time Test Circuit

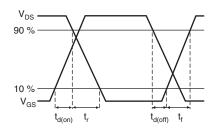


Fig. 14 - Switching Time Waveforms

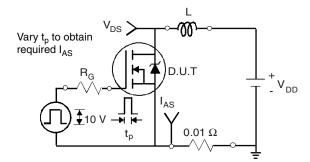


Fig. 15 - Unclamped Inductive Test Circuit

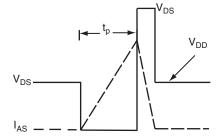


Fig. 16 - Unclamped Inductive Waveforms

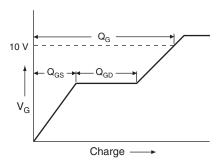


Fig. 17 - Basic Gate Charge Waveform

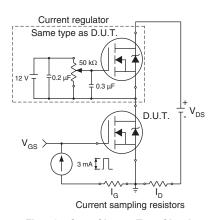
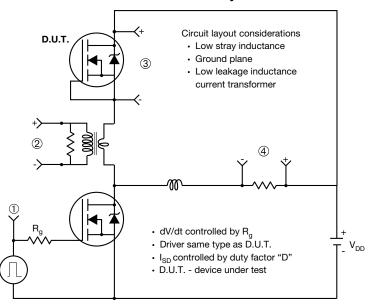


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



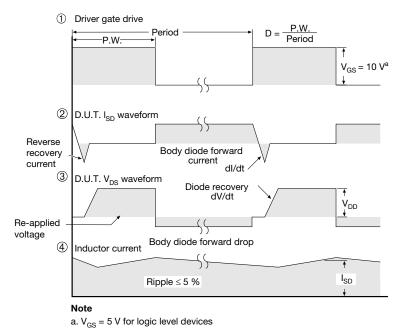
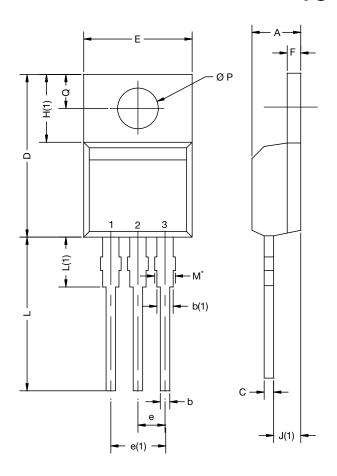


Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



Vishay

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